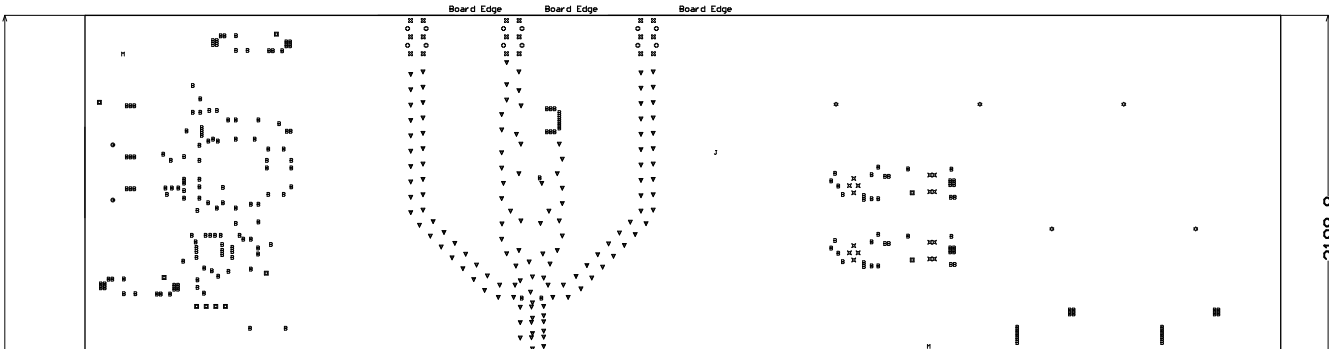


Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad	Routed Path Length
⌘	16	7.87mil (0.200mm)	PTH	Round	Pad	-
B	552	8.00mil (0.203mm)	PTH	Round	Via	-
▼	484	10.00mil (0.254mm)	PTH	Round	Via	-
⊗	60	16.00mil (0.406mm)	PTH	Round	Pad	-
⊙	2	27.56mil (0.700mm)	PTH	Slot	Pad	98.43mil (2.500mm)
■	10	28.00mil (0.711mm)	PTH	Round	Pad	-
⊕	40	45.00mil (1.143mm)	PTH	Round	Pad	-
G	2	50.00mil (1.270mm)	NPTH	Round	Pad	-
J	9	63.00mil (1.600mm)	PTH	Round	Pad	-
▽	2	96.50mil (2.451mm)	NPTH	Round	Pad	-
□	6	102.00mil (2.591mm)	PTH	Round	Pad	-
◇	2	105.91mil (2.690mm)	NPTH	Round	Pad	-
M	4	125.98mil (3.200mm)	PTH	Round	Pad	-
○	4	136.00mil (3.454mm)	PTH	Round	Pad	-
☆	5	270.00mil (6.858mm)	PTH	Round	Pad	-
1198 Total						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

NOTE:

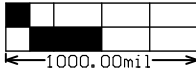
1. VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1) AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED, PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED "VIA TENTING/COVERING" REQUIREMENTS.
2. PLATING:
- A) SELECTIVE PLATING TO MIN 50uIN OF GOLD OVER 200uIN OF NICKEL. KNOOP HARDNESS 130-200
- B) REMAIN BOARD AREA PLATED IN SOFT GOLD



DESIGN INFORMATION	
MIN. TRACK WIDTH:	5.5 MIL
MIN. CLEARANCE:	4 mil
MIN. VIA PAD SIZE:	18 MIL
MINIMUM ANNULAR RING IPC Class 2 specifications	
PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 2 MIL	
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL	
MATERIAL:	
<input type="checkbox"/> FR-408	<input checked="" type="checkbox"/> FR-4 High Tg
<input type="checkbox"/> OTHER	ISOLA 370HR
THICKNESS: <input type="checkbox"/> 62.8 MIL +/-10%	<input checked="" type="checkbox"/> OTHER 80 MIL +/-10%
TOLERANCE:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2
	<input type="checkbox"/> OTHER +/-
BOW & TWIST:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2
	<input type="checkbox"/> OTHER +/-
DRILLING:	
REFERENCE:	<input checked="" type="checkbox"/> AS SHOWN
	<input checked="" type="checkbox"/> NC_DRILL FILES
PTH COPPER THICKNESS:	<input checked="" type="checkbox"/> 20-30 um
	<input type="checkbox"/> OTHER
BOARD FINISH:	
SILKSCREEN:	<input checked="" type="checkbox"/> TOP
	<input checked="" type="checkbox"/> BOTTOM

6233.0

Area for hard gold plating



6233.0

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ADC36xxEUMQUALREV: A1	SUN REV: Not in version control
LAYER NAME = FAB	TID #: N/A	
PLOT NAME = ADC36xxEUMQUAL	GENERATED : 11/6/2023 1:13:03 PM	TEXAS INSTRUMENTS

1

2

3

Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.50mil	3.5	
1	L1_Top		1.38mil		
	Dielectric 1	FR4-370HR	7.00mil	4.24	
2	L2_GND1		1.40mil		
	Dielectric 2	FR4-370HR	3.00mil	3.72	
3	L3_Pwr		1.40mil		
	Dielectric 3	ISOLA 370HR	50.00mil	4.7	
4	L4_GND2		1.40mil		
	Dielectric 4	FR4-370HR	3.00mil	3.72	
5	L5_GND3		1.40mil		
	Dielectric 5	FR4-370HR	7.00mil	4.24	
6	L6_Bottom		1.38mil		
	Bottom Solder	Solder Resist	0.50mil	3.5	
	Bottom Overlay				

Total board thickness: 79.36mil

- NOTE: THIS IS AN IMPEDANCE CONTROLLED BOARD
- ALL CORE AND PREPREG THICKNESSES ARE UP TO FAB SHOP TO SELECT.
  - EXTERNAL LAYER CU THICKNESS ARE FINISHED THICKNESS AFTER PLATING.

REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES  
PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER \_\_\_\_\_

BOARD FINISH:  
SILKSCREEN: ☒ TOP ☒ BOTTOM  
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER \_\_\_\_\_  
SOLDER RESIST COLOR: ☐ GREEN ☒ OTHER RED  
☐ MATTE ☒ SEMI-GLOSS

SURFACE FINISH: ☐ IMMERSION GOLD (ENIG) ☐ ENEPIG  
☐ IMM. TIN/SILVER OR EQUIV ☒ OTHER HARD GOLD

ARRAY/PANEL: ☒ CUT AND TRIM PER M1 BOARD OUTLINE  
☐ N.C. ROUTE ☐ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3  
☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.  
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:  
MICROSECTION: ☐ YES  
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER  
☒ 8 MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE  
☐ XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE  
☒ OUTER 12.5 MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE  
☒ LAYER 1 & 6 (OUTER LAYERS) 5.5 MIL WDE, 4 MIL SPACE  
TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE



PROJECT TITLE:  
ADC36xxEUMQUAL

DESIGNED FOR:  
Public Release

FILE NAME:  
ADC36xxQML\_Socket\_RevA.PcbDoc

ENGINEER:  
Drew Harrell

LAYOUT BY:  
XXXX

SCALE: 1.00

ALTUM DESIGNER VERSION:  
23.7.1.13

6